

# Semiconductor Manufacturing Software Tools

Semiconductor manufacturing uses a wide range of specialized software tools to design, simulate, and control the entire chip production process. These tools span design, manufacturing execution, equipment control, process simulation, yield analysis, and metrology.

## 1. EDA (Electronic Design Automation) Tools

Used for chip design before manufacturing.

Examples: Synopsys, Cadence, Siemens EDA (Mentor Graphics).

Key Functions: Circuit design and simulation (SPICE, Spectre), layout and verification (DRC, LVS), timing analysis, mask synthesis and OPC.

## 2. MES (Manufacturing Execution Systems)

Run in the fab to orchestrate production.

Examples: Applied Materials APF, Camstar, FACTORYworks, CIM.

Key Functions: WIP tracking, dispatching, recipe and parameter management, data logging, lot genealogy, and real-time dashboards.

## 3. Equipment Control and Automation

Directly controls wafer fab equipment.

Standards: SECS/GEM, E-133, Interface A.

Examples: Applied Materials, ASML, KLA, TEL, Lam Research.

Functions: Tool startup/shutdown, recipe loading, sensor data collection, fault detection and classification (FDC), predictive maintenance.

## 4. Process Simulation and Modeling

Helps optimize fabrication steps before running wafers.

Examples: Synopsys Sentaurus, Silvaco, Coventor SEMulator3D.

Functions: TCAD for transistor/device modeling, lithography and etch/deposition simulation, yield and defect density prediction.

## 5. Yield Management and Analytics

Analyzes defects, excursions, and parametric data.

Examples: KLA Klarity, PDF Solutions Exensio, Applied YieldHub.

Functions: Inline and end-of-line defect analysis, SPC, root-cause analysis for yield loss, and correlating design and process data.

## 6. Metrology and Inspection Software

Used by inspection tools for measurements and defect detection.  
Examples: KLA, Hitachi High-Tech, Applied Materials.  
Functions: Defect classification, CD-SEM analysis, overlay measurement, automated reporting.

## 7. APC and FDC

Advanced Process Control and Fault Detection & Classification.  
Examples: Applied APC, Rudolph FDC.  
Functions: Model-based and run-to-run control, detecting drifts or excursions, automated corrective actions.

## 8. Supportive IT and Data Infrastructure

Includes HPC clusters, data lakes, and cloud platforms.  
Examples: AWS, Azure, on-prem HPC clusters.  
Functions: Workflow orchestration (Kubernetes, Airflow), security and compliance, compute backbone for EDA workloads.

## Summary Table

Category	Examples	Main Role
EDA Tools	Synopsys, Cadence, Siemens EDA	Chip design & verification
MES	FACTORYworks, Camstar	Production coordination & traceability
Equipment Control	SECS/GEM, Interface A	Tool automation & sensor data collection
Process Simulation	Sentaurus, SEMulator3D	Virtual fab modeling
Yield Management	KLA Klarity, PDF Exensio	Yield analysis & defect tracking
Metrology/Inspection	KLA, Hitachi High-Tech	CD measurement & defect detection
APC/FDC	Applied APC, Rudolph FDC	Process control & excursion prevention
IT/HPC Infrastructure	AWS, on-prem HPC	Compute & data backbone

### Acronyms

EDA – Electronic Design Automation  
MES – Manufacturing Execution System  
WIP – Work-In-Progress  
FDC – Fault Detection and Classification  
TCAD – Technology Computer-Aided Design  
CD-SEM – Critical Dimension Scanning Electron Microscope  
APC – Advanced Process Control  
HPC – High Performance Computing  
ERP – Enterprise Resource Planning  
SECS/GEM – Semiconductor Equipment Communication Standard / Generic Equipment Model